

IN THE ABSTRACT:

Amend the Abstract as follows:

~~The present invention relates to a~~ In a polishing apparatus, and a semiconductor manufacturing method using the apparatus[[]], ~~Dressing~~ dressing of a grindstone surface is ~~ground~~ done by a sizing processing whereby dressing of a tool surface can be done while preventing occurrence of cracks on the grindstone surface, which ~~is the cause for~~ leads to the occurrence of scratches. Further, flatness of the surface of a dressing tool can be guaranteed because of sizing cutting-in[[]] ~~even~~ Even if a thick grindstone of a few centimeters is used, the flatness can be maintained to the end[[]] and processing with less in-face unevenness can be always carried out. Therefore, the life of the dressing tool can be greatly extended. The sizing-dressing is carried out jointly with processing of a wafer to thereby enable improvement of throughput of the apparatus as well as maintenance of a processing rate.

~~Further, the present sizing-dressing is carried out jointly with processing of a wafer to thereby enable improvement of throughput of the apparatus as well as maintenance of a processing rate.~~

~~The present apparatus and method are effective for planarization of various substrate surfaces having irregularities.~~